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| **DATA-2017: IEEE INTERNATIONAL WORKSHOP on**  **DEFECTS, ADAPTIVE TEST, YIELD AND DATA ANALYSIS**  **Will be held in conjunction with ITC 2017, on Nov. 2-3, 2017,**  **In Fort Worth, TX** | | | | https://pbs.twimg.com/profile_images/484376369644597249/E5YQkHo4_400x400.jpeg |
| **GENERAL CHAIR**  Jeffrey Roehr, Test Consultant  **PROGRAM CHAIR**  Wesley Smith, Mentor  **FINANCE CHAIR**  Sagar Kekare, KLA-Tencor  **PUBLICITY & WEB CHAIR**  Sankaran Menon, Intel  **PUBLICATIONS CHAIR**  Chintan Patel, UMBC  **PANEL CHAIR**  Anne Meixner, The Engineers' Daughter  **LOCAL ARRANGEMENTS**  David Park, Optimal+  **TEST STANDARDS CHAIR**  Al Crouch, SiliconAid  **EU LIAISON**  Dirk De Vries, Qualtera  **STEERING COMMITTEE**  Jennifer Dworak, SMU  Jeffrey Roehr, Test Consultant  Sankaran Menon, Intel  Adit Singh, Auburn Univ.  M. Tehranipoor, U of Florida  Hank Walker, Texas A&M  Hans Manhaeve, Ridgetop  Jim Plusquellic, U. NM  **PROGRAM COMMITTEE**  Rob Aitken, ARM  Nemat Bidokhti, Huawei  Sreejit Chakravarty, Intel  John Carulli, Global Foundries  Patrick Girard, LIRMM, France  Ajay Khoche, Smart Connected Systems  Mike Laisne, Dialog Semi  Rene Segers, Consultant  Amit Nahar, TI  Suriyaprakash Natarajan, Intel  Jay Orbon, Consultant  John Potter, Global Foundries  Rajesh Raina, NXP  Claude Thibeault, ETS, Canada  Li C. Wang, UCSB  Xiaoqing Wen, KIT, Japan  Qiang Xu, CUHK, Hong Kong | **CALL FOR PAPERS AND PARTICIPATION**  **THEME: “Data in the Product Lifecycle”**  In test, we use data every day. Yield data, throughput data, statistical data, reliability data, outlier data, general production data are all in everyday use. However, data means much more than that. Advances in our industry allow data from wafer fab to be reused in studying system level test results. Field failure studies now routinely uses wafer probe data to understand root cause. Data has now become a product life cycle requirement—cradle to grave. Today access to the data has become an issue; the control and sharing of data among business partners. How to efficiently process data to extract the golden nuggets of useful information amid the gigabytes of unimportant noise remains a focus and a challenge for test professionals.    The Organizing Committee for the DATA-2017 Workshop is soliciting papers in: semiconductor test, yield analysis, product learning, and quality improvement. Of particular interest are advanced techniques and new tools for the use of data during the entire product life cycle, with special attention to how data can be used to change and alter test flows and decisions (adaptive test). Preference will be given to real-world case studies.    Ideas or proposals for Embedded Tutorials, Debates, Panel Discussions and Poster style “Spot-Light” presentations describing industrial experiences or research are also invited. | | | |
| **Suggested Topics**  Real Time Analysis Methods  Real Time Test Process Monitoring  Yield Learning and Analysis  Analog Fault Modeling and Coverage  Analog Effects in Digital Logic  Embedded Instrumentation (iJTAG)  Advanced DPPM Reduction & Reliability  Improvement Techniques | | Data Acquisition & Transport  Adaptive Test for Product Engineers  Data Analysis Methods, Including  Multivariate Data  Fault Localization and Diagnosis  Data Storage and Security  I/O Test, Tuning, and Adjustment  Product and Project Case studies | |
| To present at the workshop, send to [smith.wesley@siemens.com](mailto:smith.wesley@siemens.com) a PDF version of an extended abstract or a full paper (Max 10 pages, double column, 11pt font size, [IEEE proceeding format](http://www.ieee.org/conferences_events/conferences/publishing/templates.html) ) by **September 20, 2017**. Each submission should include full name and address of each author, affiliation, telephone number, and Email address. Camera-ready papers for inclusion in the digest of papers will be due on **October 16, 2017**. | | | |
| **AUTHOR’S SCHEDULE** Web-site at: <http://DATA.tttc-events.org/>   |  |  | | --- | --- | | **Submission Date:** | **September 20, 2017** | | **Notification of Acceptance:**  **Camera Ready Paper (.pdf):** | **October 2, 2017**  **October 16, 2017** | | **Final Presentation Slides (.ppt):** | **October 23, 2017** | | | | |
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| **DATA-2017 is sponsored by:**   |  |  |  | | --- | --- | --- | | IEEE | TTTC | IEEE CS | | | | |